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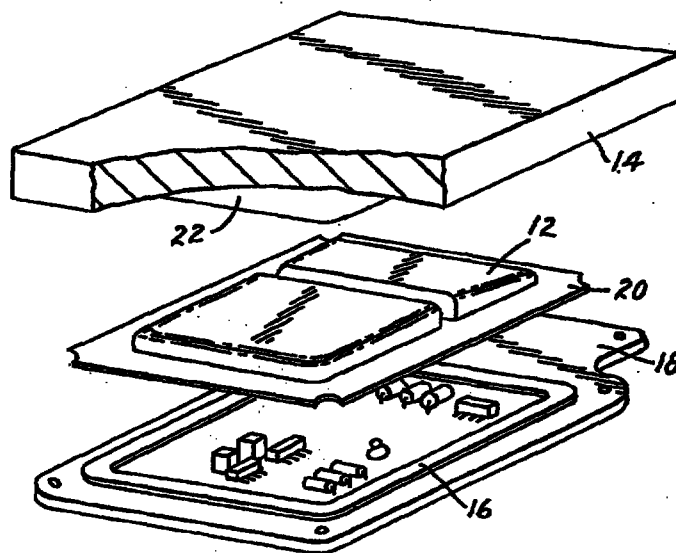
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(54) Title: EMI SHIELDING ENCLOSURES



(57) Abstract

An EMI shielding enclosure, for an electronic assembly, comprising a ground plane of a printed circuit connected to a shaped EMI shielding cover. The cover results from thermoforming a composite sheet of several layers, including a carrier for a fibrous metal mat that has fibers substantially surrounded by a fiber-coat. Connection of the cover to the ground plane, to form the EMI shielding enclosure, requires the fiber-coat to adhere to the printed circuit in the vicinity of the ground plane.